

IRG7PSH50UDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Features

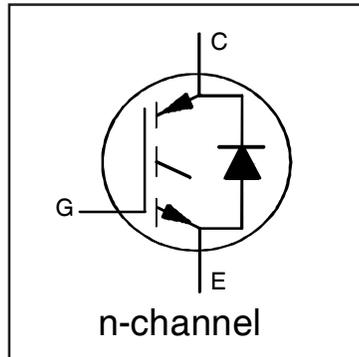
- Low $V_{CE(ON)}$ trench IGBT technology
- Low switching losses
- Square RBSOA
- 100% of the parts tested for I_{LM} ①
- Positive $V_{CE(ON)}$ temperature co-efficient
- Ultra fast soft recovery co-pak diode
- Tight parameter distribution
- Lead-Free

Benefits

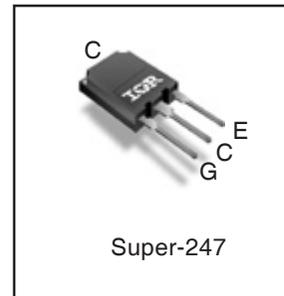
- High efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to low $V_{CE(ON)}$ and low switching losses
- Rugged transient performance for increased reliability
- Excellent current sharing in parallel operation

Applications

- U.P.S.
- Welding
- Solar Inverter
- Induction Heating



| |
|----------------------------------|
| $V_{CES} = 1200V$ |
| $I_{NOMINAL} = 50A$ |
| $T_{J(max)} = 150^{\circ}C$ |
| $V_{CE(on)} \text{ typ.} = 1.7V$ |



| | | |
|----------|-----------|----------|
| G | C | E |
| Gate | Collector | Emitter |

Absolute Maximum Ratings

| | Parameter | Max. | Units | |
|----------------------------|---|-----------------------------------|-------------|---|
| V_{CES} | Collector-to-Emitter Voltage | 1200 | V | |
| $I_C @ T_C = 25^{\circ}C$ | Continuous Collector Current (Silicon Limited) | 116 | A | |
| $I_C @ T_C = 100^{\circ}C$ | Continuous Collector Current (Silicon Limited) | 70 | | |
| $I_{NOMINAL}$ | Nominal Current | 50 | | |
| I_{CM} | Pulse Collector Current, $V_{GE} = 15V$ | 150 | | |
| I_{LM} | Clamped Inductive Load Current, $V_{GE} = 20V$ ① | 200 | | |
| $I_F @ T_C = 25^{\circ}C$ | Diode Continuous Forward Current | 116 | | |
| $I_F @ T_C = 100^{\circ}C$ | Diode Continuous Forward Current | 70 | | |
| I_{FM} | Diode Maximum Forward Current ② | 200 | | |
| V_{GE} | Continuous Gate-to-Emitter Voltage | ± 30 | | V |
| $P_D @ T_C = 25^{\circ}C$ | Maximum Power Dissipation | 462 | | W |
| $P_D @ T_C = 100^{\circ}C$ | Maximum Power Dissipation | 185 | | |
| T_J T_{STG} | Operating Junction and Storage Temperature Range | -55 to +150 | $^{\circ}C$ | |
| | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) | | |
| | Mounting Torque, 6-32 or M3 Screw | 10 lbf-in (1.1 N-m) | | |

Thermal Resistance

| | Parameter | Min. | Typ. | Max. | Units |
|-------------------------|--|------|------|------|---------------|
| $R_{\theta JC}$ (IGBT) | Thermal Resistance Junction-to-Case-(each IGBT) ④ | — | — | 0.27 | $^{\circ}C/W$ |
| $R_{\theta JC}$ (Diode) | Thermal Resistance Junction-to-Case-(each Diode) ④ | — | — | 0.37 | |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink (flat, greased surface) | — | 0.24 | — | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (typical socket mount) | — | 40 | — | |

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|---|------|------|------|---------------|--|
| $V_{(BR)CES}$ | Collector-to-Emitter Breakdown Voltage | 1200 | — | — | V | $V_{GE} = 0V, I_C = 100\mu\text{A}$ ③ |
| $\Delta V_{(BR)CES}/\Delta T_J$ | Temperature Coeff. of Breakdown Voltage | — | 1.0 | — | V/°C | $V_{GE} = 0V, I_C = 1.0\text{mA}$ (25°C-150°C) |
| $V_{CE(on)}$ | Collector-to-Emitter Saturation Voltage | — | 1.7 | 2.0 | V | $I_C = 50A, V_{GE} = 15V, T_J = 25^\circ\text{C}$ |
| | | — | 2.0 | — | | $I_C = 50A, V_{GE} = 15V, T_J = 150^\circ\text{C}$ |
| $V_{GE(th)}$ | Gate Threshold Voltage | 3.0 | — | 6.0 | V | $V_{CE} = V_{GE}, I_C = 2.0\text{mA}$ |
| $\Delta V_{GE(th)}/\Delta T_J$ | Threshold Voltage temp. coefficient | — | -17 | — | mV/°C | $V_{CE} = V_{GE}, I_C = 1.0\text{mA}$ (25°C - 150°C) |
| g_{fe} | Forward Transconductance | — | 55 | — | S | $V_{CE} = 50V, I_C = 50A, PW = 30\mu\text{s}$ |
| I_{CES} | Collector-to-Emitter Leakage Current | — | 2.0 | 100 | μA | $V_{GE} = 0V, V_{CE} = 1200V$ |
| | | — | 3700 | — | | $V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$ |
| V_{FM} | Diode Forward Voltage Drop | — | 3.0 | 3.9 | V | $I_F = 50A$ |
| | | — | 2.7 | — | | $I_F = 50A, T_J = 150^\circ\text{C}$ |
| I_{GES} | Gate-to-Emitter Leakage Current | — | — | ±200 | nA | $V_{GE} = \pm 30V$ |

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------|--------------------------------------|-------------|------|------|---------------|--|
| Q_g | Total Gate Charge (turn-on) | — | 290 | 440 | nC | $I_C = 50A$ $V_{GE} = 15V$ $V_{CC} = 600V$ |
| Q_{ge} | Gate-to-Emitter Charge (turn-on) | — | 40 | 60 | | |
| Q_{gc} | Gate-to-Collector Charge (turn-on) | — | 110 | 170 | | |
| E_{on} | Turn-On Switching Loss | — | 3600 | 4600 | μJ | $I_C = 50A, V_{CC} = 600V, V_{GE} = 15V$ $R_G = 5.0\Omega, L = 200\mu\text{H}, T_J = 25^\circ\text{C}$ Energy losses include tail & diode reverse recovery |
| E_{off} | Turn-Off Switching Loss | — | 2200 | 3200 | | |
| E_{total} | Total Switching Loss | — | 5800 | 7800 | | |
| $t_{d(on)}$ | Turn-On delay time | — | 35 | 55 | ns | |
| t_r | Rise time | — | 40 | 60 | | |
| $t_{d(off)}$ | Turn-Off delay time | — | 430 | 500 | | |
| t_f | Fall time | — | 45 | 65 | | |
| E_{on} | Turn-On Switching Loss | — | 5080 | — | | |
| E_{off} | Turn-Off Switching Loss | — | 3370 | — | | |
| E_{total} | Total Switching Loss | — | 8450 | — | | |
| $t_{d(on)}$ | Turn-On delay time | — | 30 | — | ns | |
| t_r | Rise time | — | 40 | — | | |
| $t_{d(off)}$ | Turn-Off delay time | — | 480 | — | | |
| t_f | Fall time | — | 170 | — | | |
| C_{ies} | Input Capacitance | — | 6000 | — | pF | $V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0\text{Mhz}$ |
| C_{oes} | Output Capacitance | — | 300 | — | | |
| C_{res} | Reverse Transfer Capacitance | — | 130 | — | | |
| RBSOA | Reverse Bias Safe Operating Area | FULL SQUARE | | | | $T_J = 150^\circ\text{C}, I_C = 200A$ $V_{CC} = 960V, V_p = 1200V$ $R_g = 5.0\Omega, V_{GE} = +20V \text{ to } 0V$ |
| E_{rec} | Reverse Recovery Energy of the Diode | — | 1510 | — | μJ | $T_J = 150^\circ\text{C}$ |
| t_{rr} | Diode Reverse Recovery Time | — | 190 | — | ns | $V_{CC} = 600V, I_F = 5.0A$ |
| I_{rr} | Peak Reverse Recovery Current | — | 5760 | — | A | $R_g = 5.0\Omega, L = 1.0\text{mH}$ |

Notes:

- ① $V_{CC} = 80\% (V_{CES}), V_{GE} = 20V, L = 200\mu\text{H}, R_G = 5.0\Omega$.
- ② Pulse width limited by max. junction temperature.
- ③ Refer to AN-1086 for guidelines for measuring $V_{(BR)CES}$ safely.
- ④ R_θ is measured at T_J of approximately 90°C .

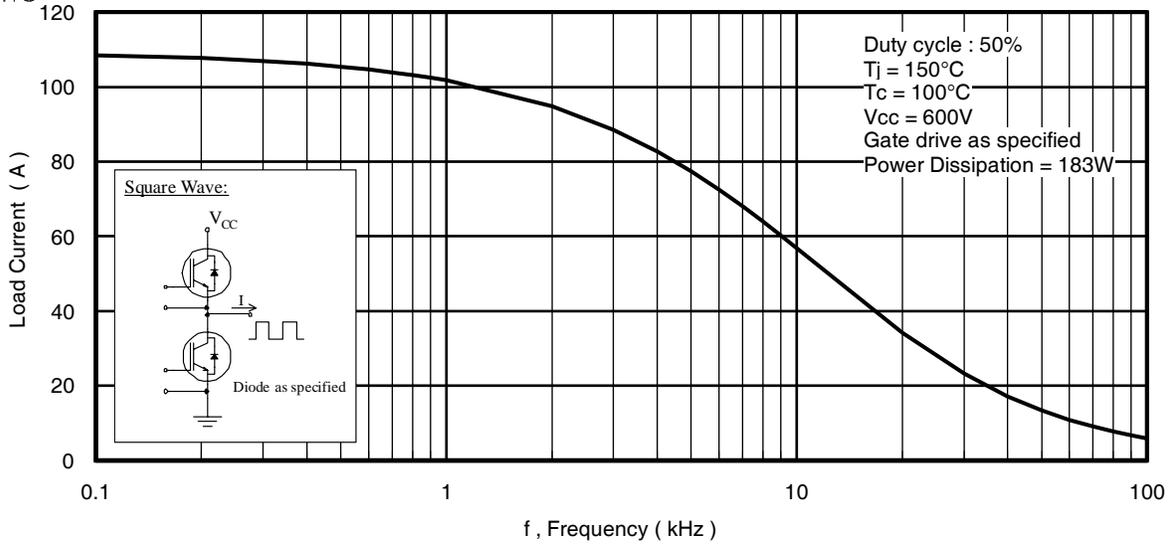


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

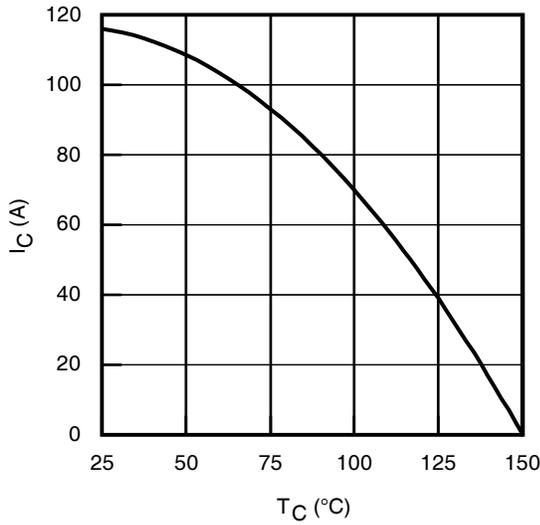


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

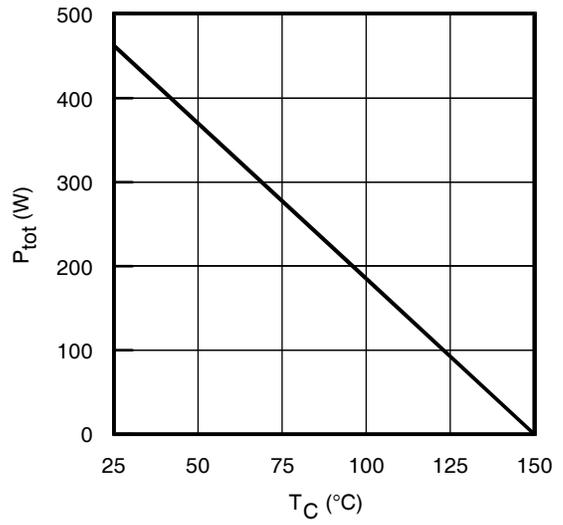


Fig. 2 - Power Dissipation vs. Case Temperature

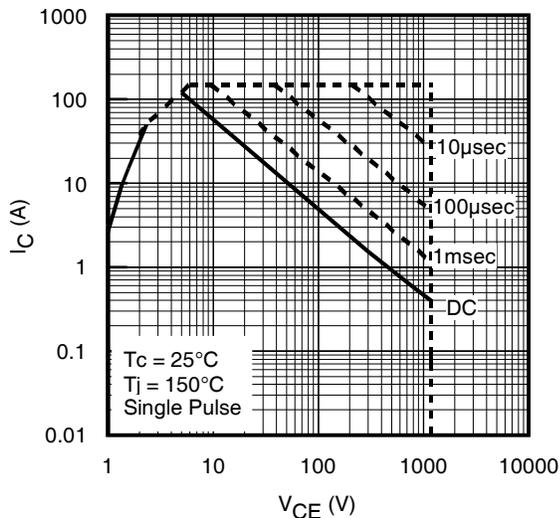


Fig. 3 - Forward SOA
 $T_C = 25^\circ\text{C}$, $T_J \leq 150^\circ\text{C}$; $V_{GE} = 15\text{V}$

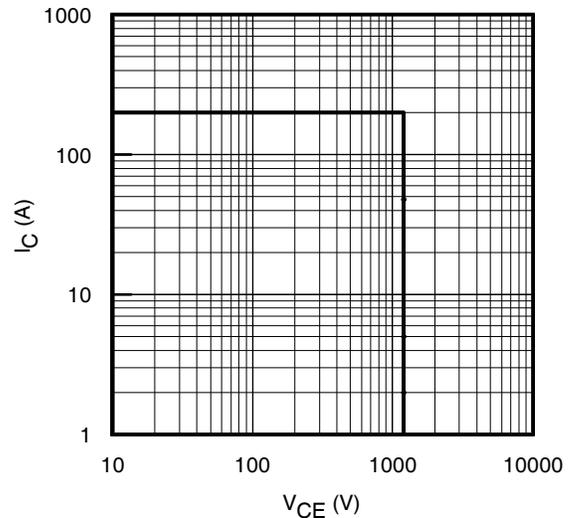


Fig. 4 - Reverse Bias SOA
 $T_J = 150^\circ\text{C}$; $V_{GE} = 20\text{V}$

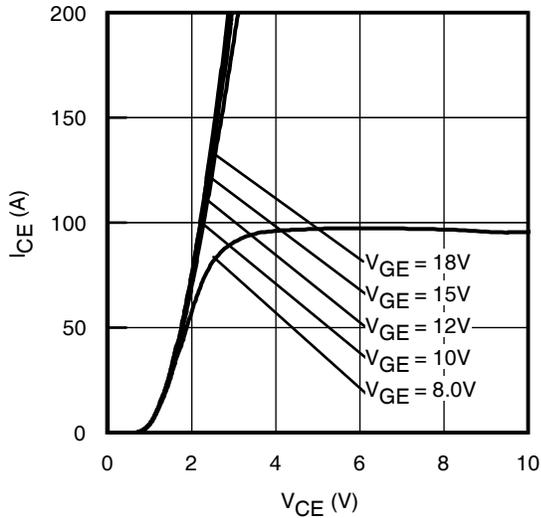


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^\circ\text{C}$; $t_p = 30\mu\text{s}$

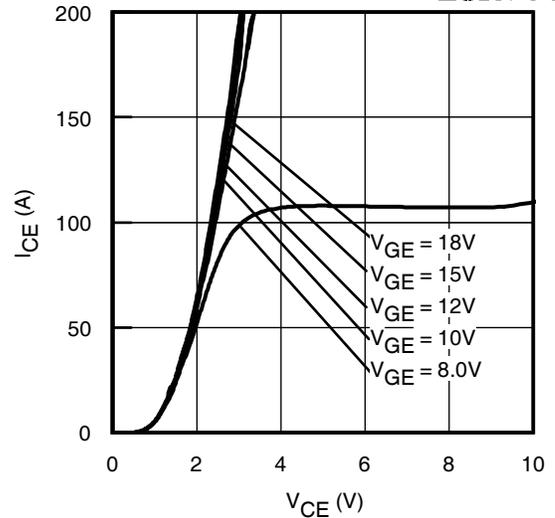


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}$; $t_p = 30\mu\text{s}$

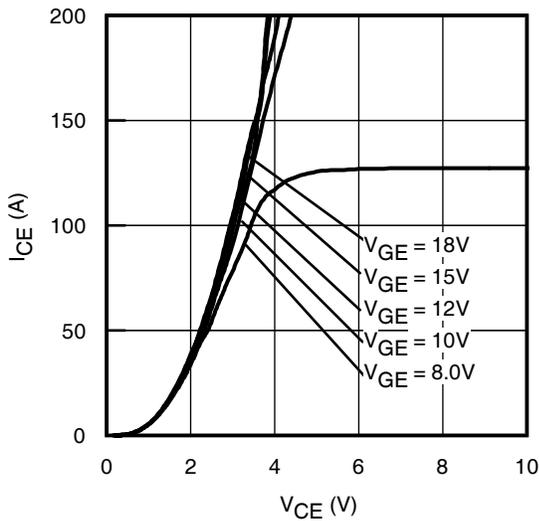


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 150^\circ\text{C}$; $t_p = 30\mu\text{s}$

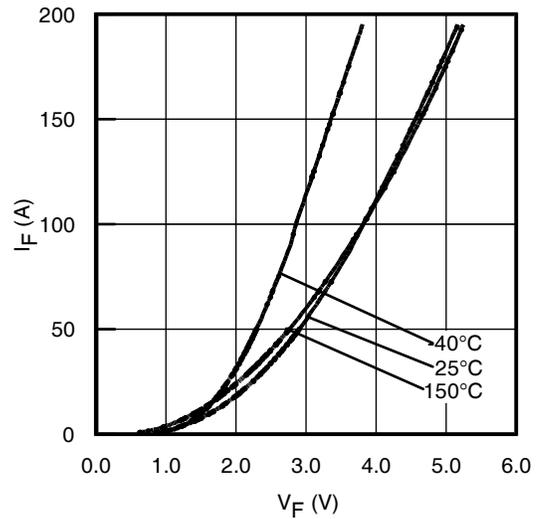


Fig. 8 - Typ. Diode Forward Characteristics
 $t_p = 30\mu\text{s}$

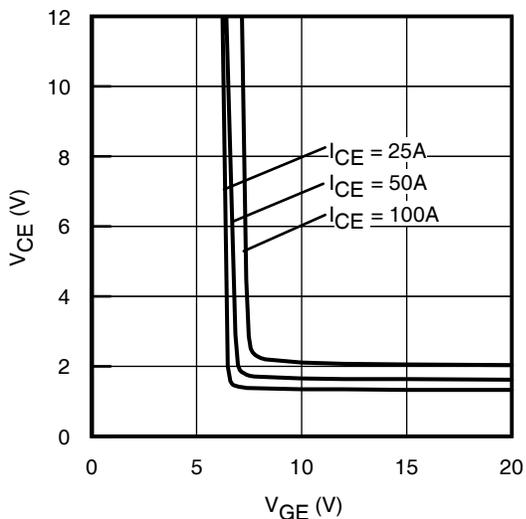


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

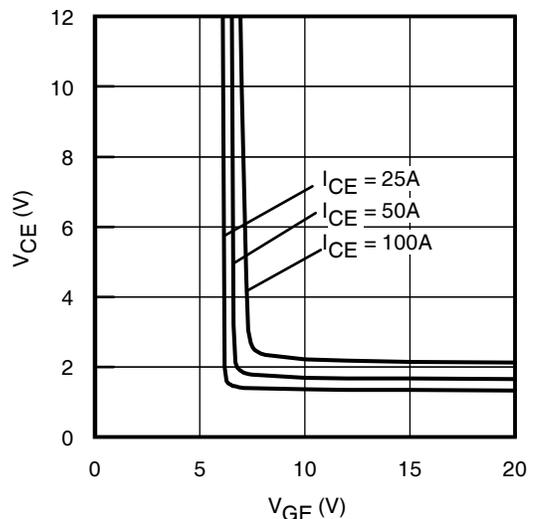


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

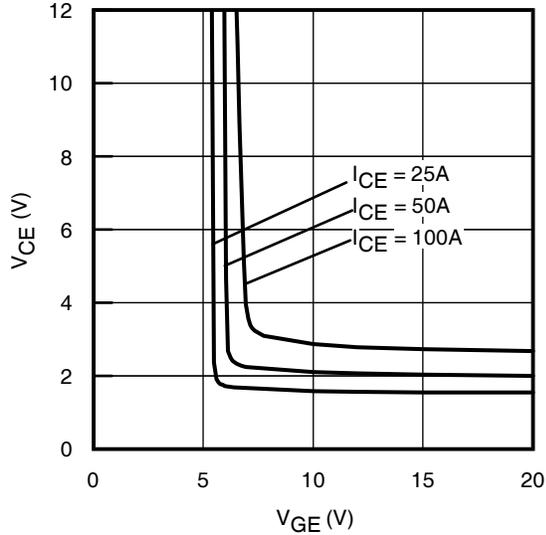


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 150^\circ\text{C}$

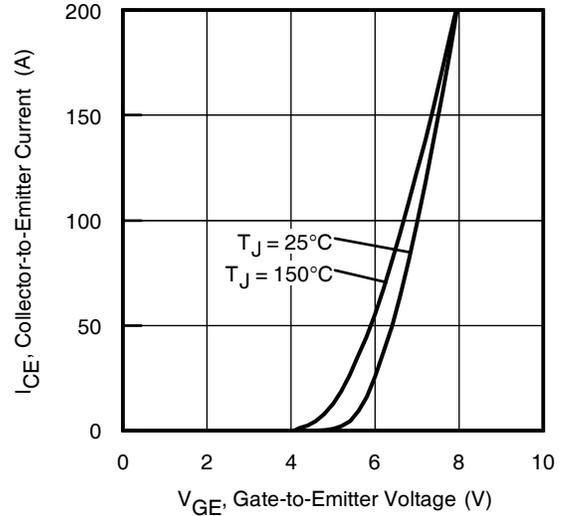


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 30\mu\text{s}$

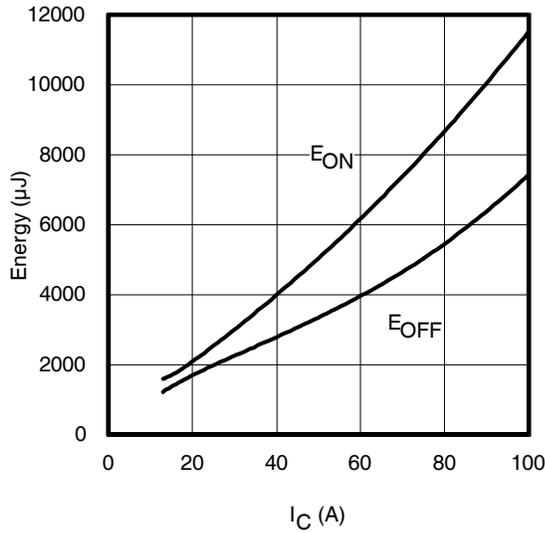


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 150^\circ\text{C}$; $L = 200\mu\text{H}$; $V_{CE} = 600\text{V}$, $R_G = 5.0\Omega$; $V_{GE} = 15\text{V}$

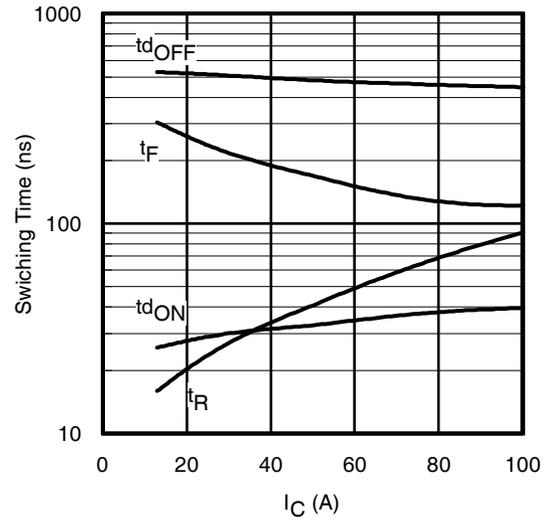


Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 150^\circ\text{C}$; $L = 200\mu\text{H}$; $V_{CE} = 600\text{V}$, $R_G = 5.0\Omega$; $V_{GE} = 15\text{V}$

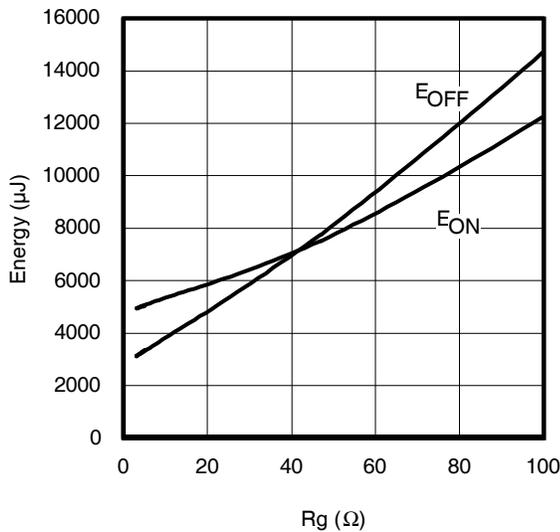


Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 150^\circ\text{C}$; $L = 200\mu\text{H}$; $V_{CE} = 600\text{V}$, $I_{CE} = 50\text{A}$; $V_{GE} = 15\text{V}$

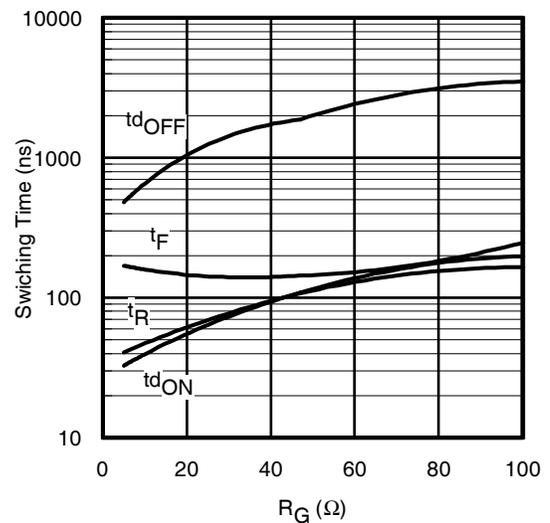


Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 150^\circ\text{C}$; $L = 200\mu\text{H}$; $V_{CE} = 600\text{V}$, $I_{CE} = 50\text{A}$; $V_{GE} = 15\text{V}$

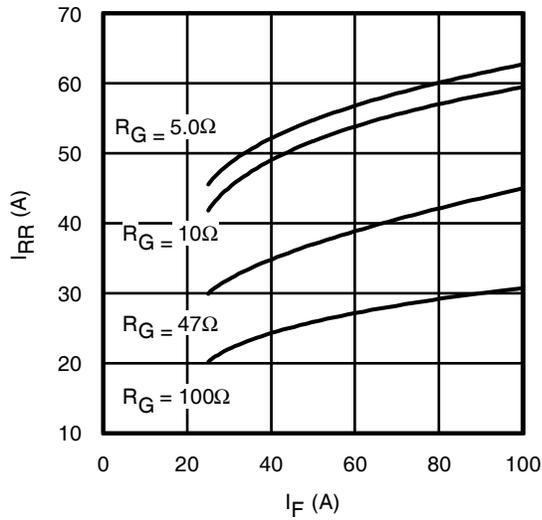


Fig. 17 - Typ. Diode I_{RR} vs. I_F
 $T_J = 150^\circ\text{C}$

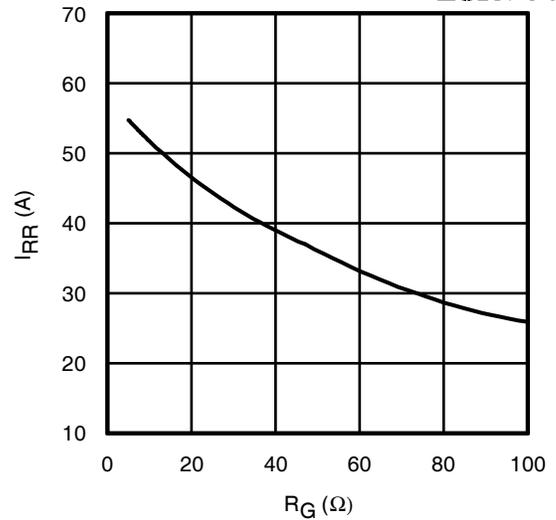


Fig. 18 - Typ. Diode I_{RR} vs. R_G
 $T_J = 150^\circ\text{C}$

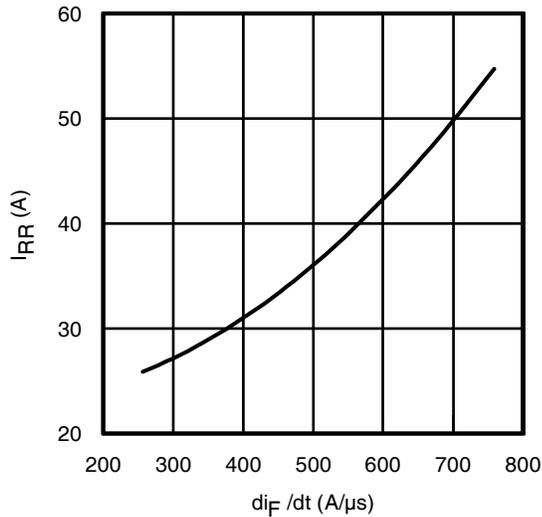


Fig. 19 - Typ. Diode I_{RR} vs. di_F/dt
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; I_F = 50\text{A}; T_J = 150^\circ\text{C}$

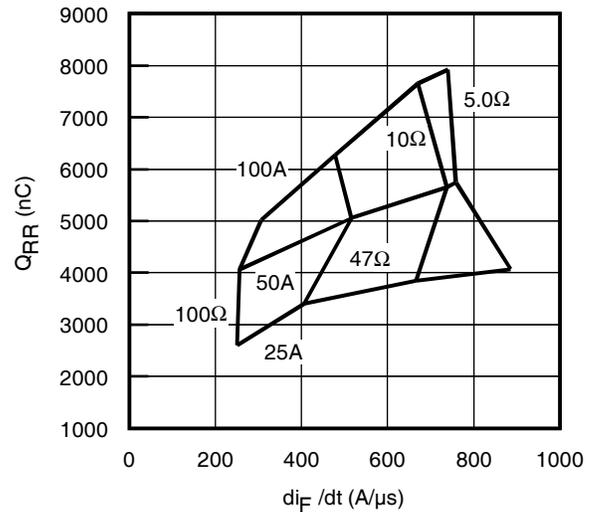


Fig. 20 - Typ. Diode Q_{RR} vs. di_F/dt
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; T_J = 150^\circ\text{C}$

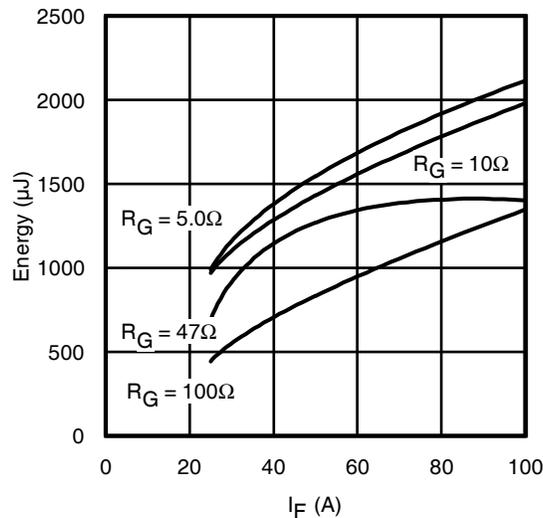


Fig. 21 - Typ. Diode E_{RR} vs. I_F
 $T_J = 150^\circ\text{C}$

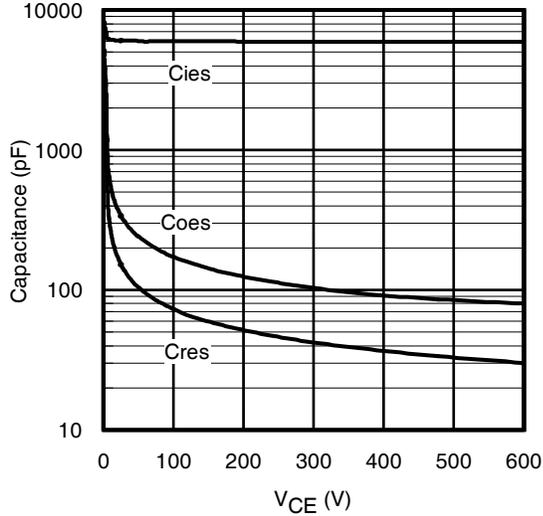


Fig. 22 - Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0V$; $f = 1MHz$

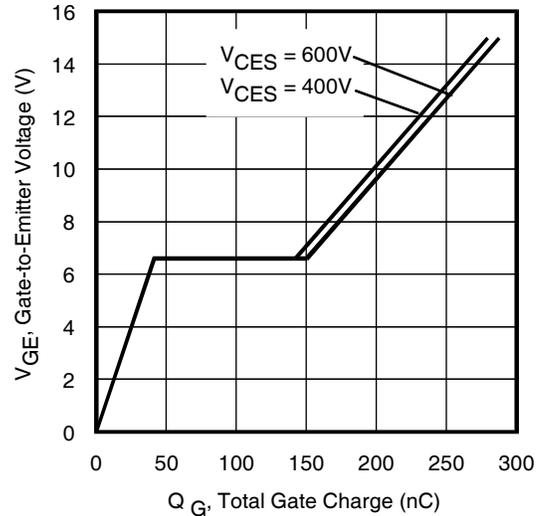


Fig. 23 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 50A$

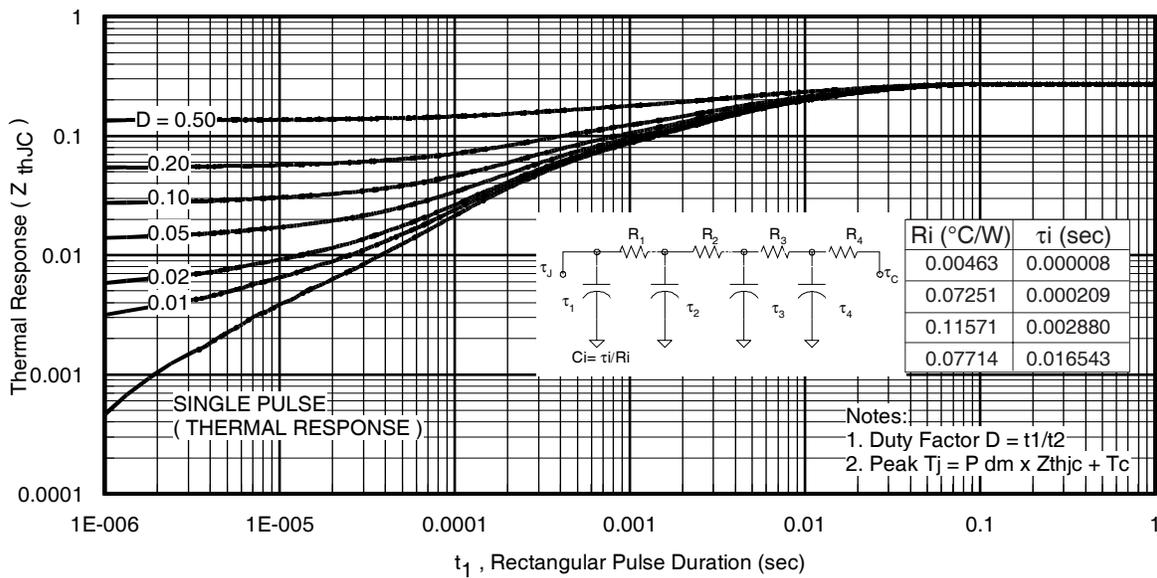


Fig. 24. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

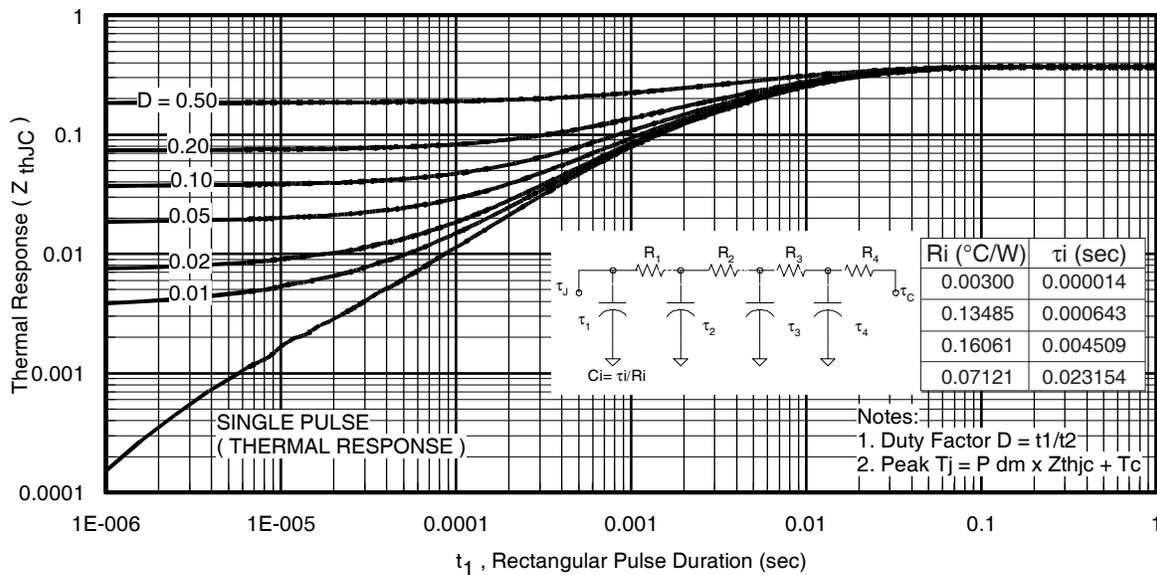


Fig. 25. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

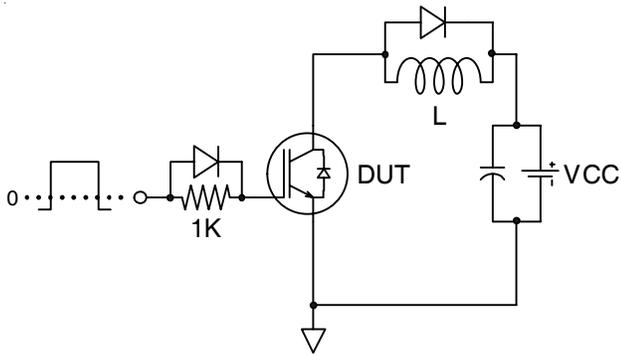


Fig.C.T.1 - Gate Charge Circuit (turn-off)

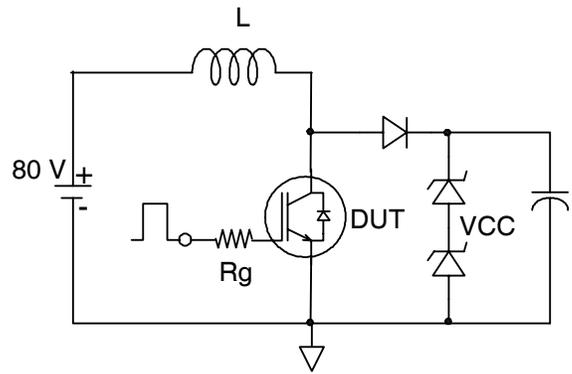


Fig.C.T.2 - RBSOA Circuit

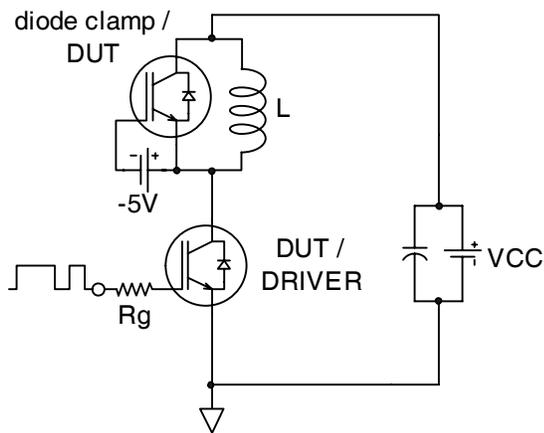


Fig.C.T.3 - Switching Loss Circuit

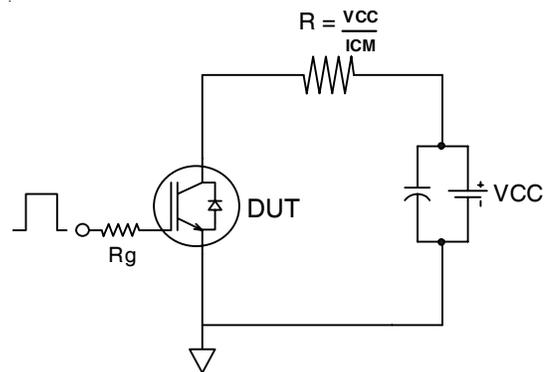


Fig.C.T.4 - Resistive Load Circuit

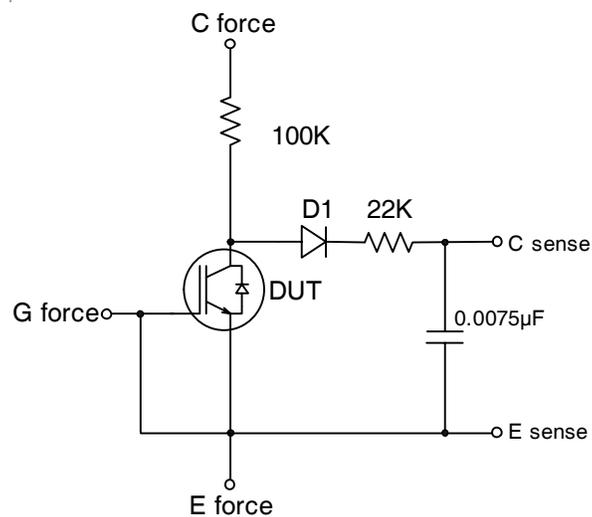


Fig.C.T.5 - BVCES Filter Circuit

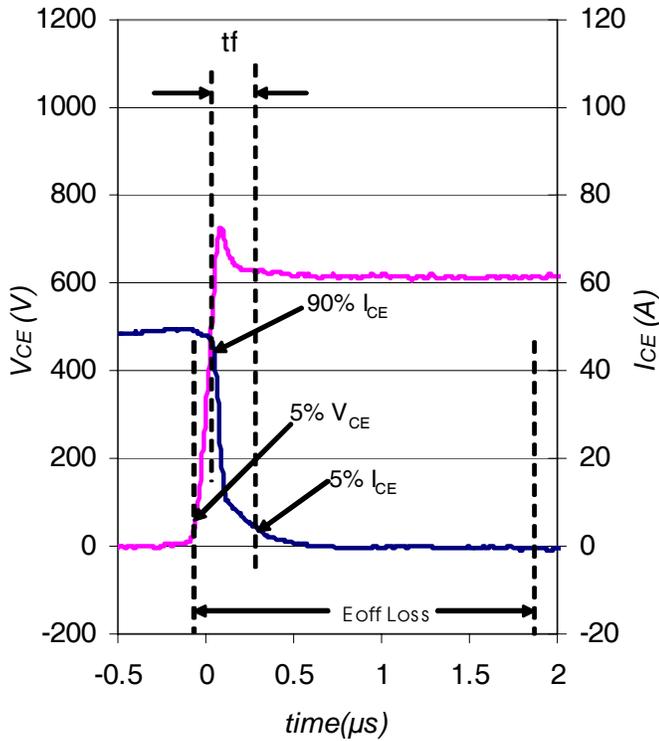


Fig. WF1 - Typ. Turn-off Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

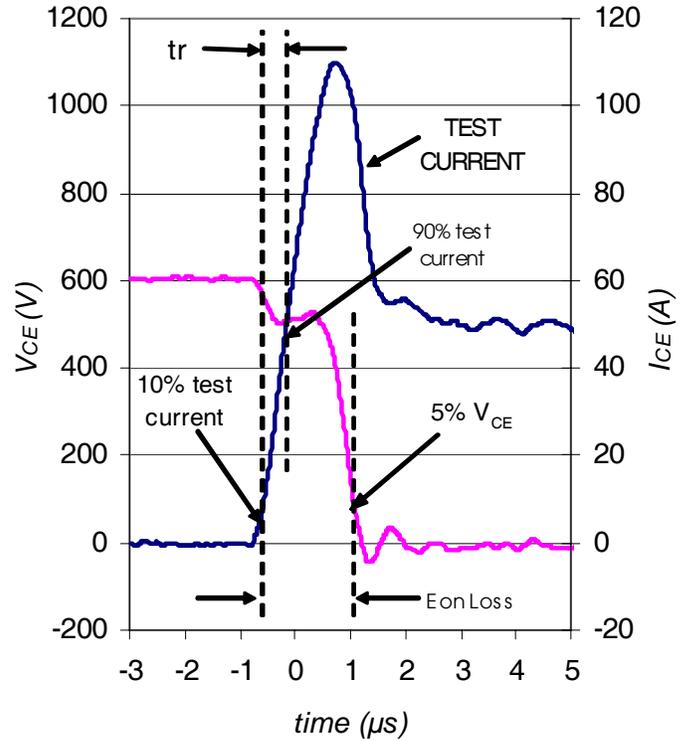


Fig. WF2 - Typ. Turn-on Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

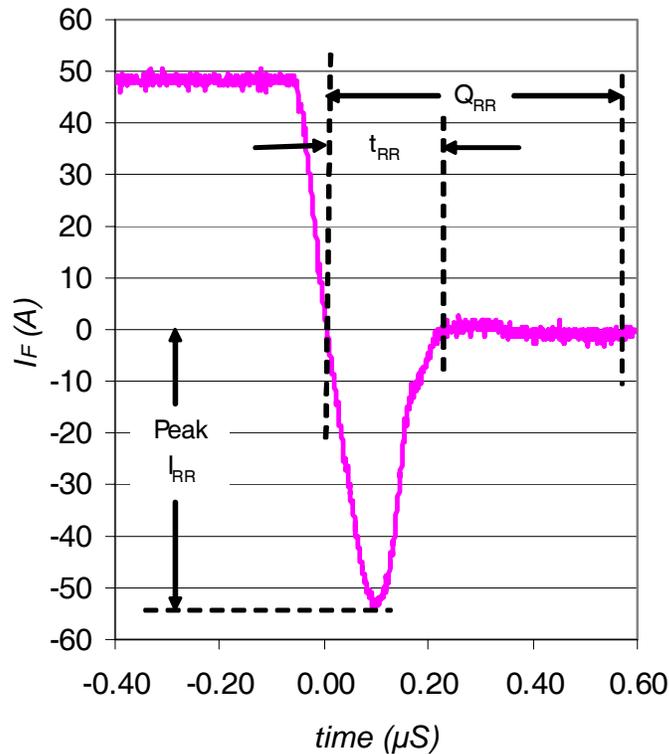
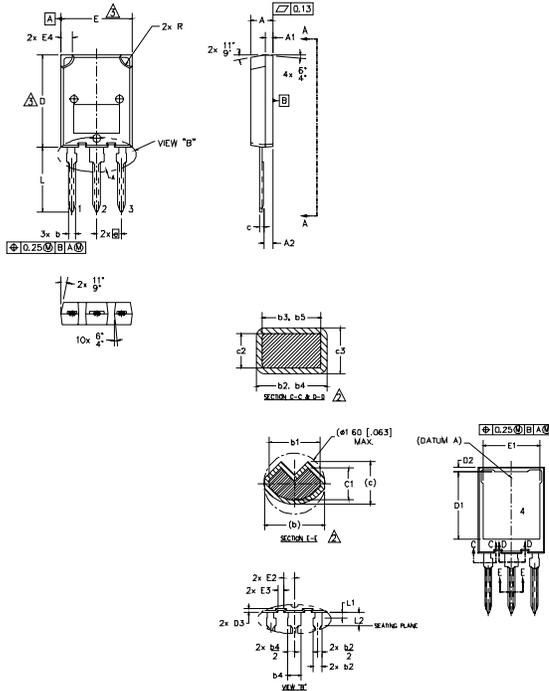


Fig. WF3 - Typ. Diode Recovery Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

IRG7PSH50UDPbF

Case Outline and Dimensions — Super-247



- NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M-1994
 2. DIMENSIONS b1, b3, b5, c1 & c3 APPLY TO BASE METAL ONLY.
 3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTER EXTREMES OF THE PLASTIC BODY.
 4. ALL DIMENSIONS SHOWN IN MILLIMETERS.
 5. CONTROLLING DIMENSION: MILLIMETER.
 6. OUTLINE CONFORMS TO JEDEC OUTLINE TO-274AA

| SYMBOL | DIMENSIONS | | | | NOTES |
|--------|-------------|-------|----------|------|-------|
| | MILLIMETERS | | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.50 | 5.50 | .177 | .217 | |
| A1 | 1.45 | 2.15 | .057 | .085 | |
| A2 | 1.65 | 2.35 | .065 | .093 | |
| b | 1.45 | 1.60 | .054 | .063 | |
| b1 | 1.40 | 1.50 | .055 | .059 | 2 |
| b2 | 2.00 | 2.40 | .079 | .094 | |
| b3 | 1.95 | 2.35 | .077 | .093 | 2 |
| b4 | 3.00 | 3.15 | .118 | .124 | |
| b5 | 2.95 | 3.35 | .116 | .132 | 2 |
| c | 1.10 | 1.30 | .043 | .051 | |
| c1 | 0.90 | 1.10 | .035 | .043 | 2 |
| c2 | 0.65 | 0.85 | .026 | .033 | |
| c3 | 0.50 | 0.70 | .020 | .028 | 2 |
| D | 19.80 | 20.80 | .780 | .819 | 3 |
| D1 | 15.50 | 16.10 | .610 | .634 | |
| D2 | 0.70 | 1.30 | .028 | .051 | |
| D3 | 0.75 | 1.25 | .030 | .049 | |
| E | 15.10 | 16.10 | .594 | .634 | 3 |
| E1 | 13.30 | 13.90 | .524 | .547 | |
| E2 | 2.25 | 2.70 | .089 | .109 | |
| E3 | 1.20 | 1.70 | .047 | .067 | |
| E4 | 2.00 | 3.00 | .079 | .118 | |
| e | 5.45 BSC | | .215 BSC | | |
| L | 13.80 | 14.80 | .535 | .583 | |
| L1 | 1.00 | 1.60 | .039 | .063 | |
| L2 | 3.85 | 4.25 | .152 | .167 | |
| R | 2.00 | 3.00 | .079 | .118 | |

LEAD ASSIGNMENTS

MOSFET

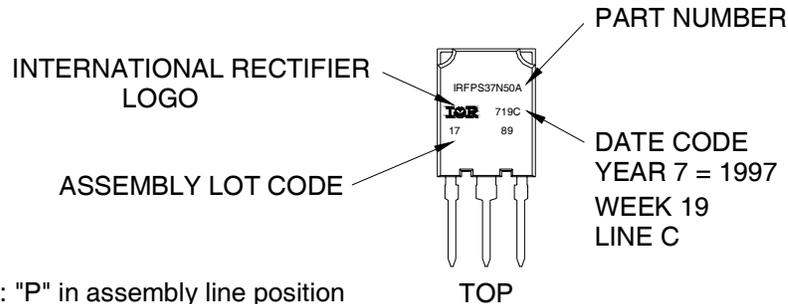
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

Super-247 (TO-274AA) Part Marking Information

EXAMPLE: THIS IS AN IRFPS37N50A WITH
ASSEMBLY LOT CODE 1789
ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"



Note: "P" in assembly line position indicates "Lead-Free"

Super-247 package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial market.
Qualification Standards can be found on IR's Web site.

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